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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy them if

1. Name of conveying party(ies)  
  
Motoki NAKADE, Jun TANAKA, Yoshito SHIRAISHI, Etsuo KURODA  
  
Additional name(s) of conveying party(ies) attached?  
\_ Yes X No

2. Name and address of receiving party(ies)  
  
Name: SONY CORPORATION  
7-35 Kitashinagawa 6-chome  
Shinagawa-Ku, Tokyo 141-0001, Japan  
  
Additional name(s) & address(es) attached? \_ Yes X No

J1036 U.S. PATENT TO 09/817599 03/26/01

3. Nature of conveyance:  
  
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Execution Date: February 28, February 27, February 27 and March 1, 2001

3/26/01

4. Application number(s) or patent number(s): 09817599  
  
If this document is being filed together with a new application, the execution date of the application is: February 28, February 27, February 27 and March 1, 2001  
  
A. Patent Application No.(s) \_\_\_\_\_ filed \_\_\_\_\_  
  
Additional numbers attached? \_ Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed:  
  
Name: WILLIAM S. FROMMER  
  
Internal Address: FROMMER LAWRENCE & HAUG LLP  
  
Street Address: 745 FIFTH AVENUE  
  
City: NEW YORK State: N.Y. Zip: 10151

6. Total number of applications and patents involved . . . . . 1  
  
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**ASSIGNMENT**

**WHEREAS**, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in **COMMUNICATION METHOD, COMMUNICATION SERVICE APPARATUS, COMMUNICATION TERMINAL DEVICE AND COMMUNICATION SYSTEM**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

**AND WHEREAS**, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

**NOW THEREFORE**, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: \_\_\_\_\_, Filing Date: \_\_\_\_\_.

This assignment executed on the dates indicated below.

MOTOKI NAKADE

Name of first or sole inventor  
TOKYO, JAPAN

Execution date of U.S. Patent Application

Residence of first or sole inventor

*Motoki Nakade*  
Signature of first or sole inventor

February 28, 2001  
Date of this assignment

JUN TANAKA

Name of second inventor  
TOKYO, JAPAN

Execution date of U.S. Patent Application

Residence of second inventor

*Jun Tanaka*  
Signature of second inventor

February 27, 2001  
Date of this assignment

YOSHITO SHIRAIISHI

Name of third inventor  
KANAGAWA, JAPAN

Execution date of U.S. Patent Application

Residence of third inventor

*Yoshito Shiraiishi*  
Signature of third inventor

February 27, 2001  
Date of this assignment

ADDITIONAL INVENTOR(S) ON NEXT PAGE

ETSUO KURODA

Name of fourth inventor TOKYO, JAPAN	Execution date of U.S. Patent Application
Residence of fourth inventor	
Signature of fourth inventor <i>Etsuo Kuroda</i>	Date of this assignment <i>March 1, 2001</i>
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
Signature of fifth inventor	Date of this assignment
Name of sixth inventor	Execution date of U.S. Patent Application
Residence of sixth inventor	
Signature of sixth inventor	Date of this assignment
Name of seventh inventor	Execution date of U.S. Patent Application
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Name of eighth inventor	Execution date of U.S. Patent Application
Residence of eighth inventor	
Signature of eighth inventor	Date of this assignment
Name of ninth inventor	Execution date of U.S. Patent Application
Residence of ninth inventor	
Signature of ninth inventor	Date of this assignment